

## Features

- Advanced Trench MOS Technology
- 100% EAS Guaranteed
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Green Device Available

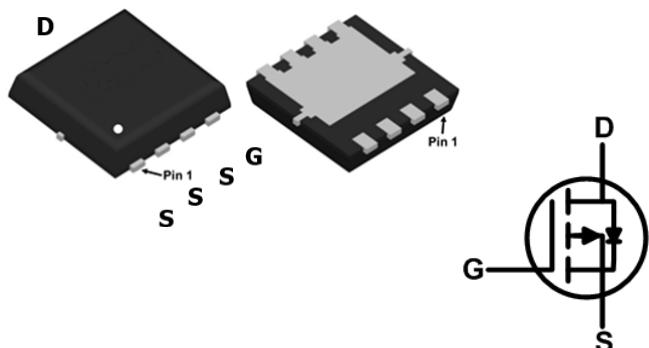
## Product Summary

BVDSS	RDS(ON)	ID
-100V	95mΩ	-14A

## Applications

- High Frequency Switching and Synchronous Rectification.
- DC/DC Converter

## DFN3x3 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-100	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>c</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	-14	A
I <sub>D</sub> @T <sub>c</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	-8.7	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	-56	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	157.2	mJ
I <sub>AS</sub>	Avalanche Current	18.9	A
P <sub>D</sub> @T <sub>c</sub> =25°C	Total Power Dissipation <sup>4</sup>	31	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	65	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	4	°C/W

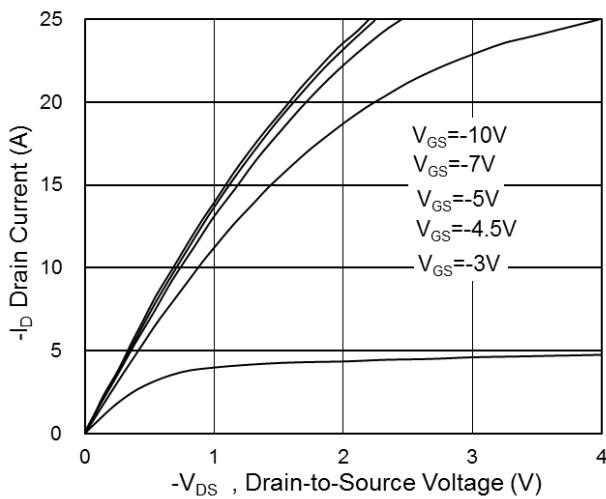
**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=-250\mu\text{A}$	-100	---	---	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=-10\text{V}$ , $I_D=-10\text{A}$	---	---	95	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$ , $I_D=-8\text{A}$	---	---	110	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=-250\mu\text{A}$	-1.2	-1.7	-2.5	V
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-100\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	-50	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=-10\text{V}$ , $I_D=-10\text{A}$	---	24	---	S
$Q_g$	Total Gate Charge	$V_{\text{DS}}=-50\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $I_D=-10\text{A}$	---	44.5	---	nC
$Q_{\text{gs}}$	Gate-Source Charge		---	9.13	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	5.93	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=-50\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $R_G=3.3\Omega$ , $I_D=-10\text{A}$	---	12	---	ns
$T_r$	Rise Time		---	27.4	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	79	---	
$T_f$	Fall Time		---	53.6	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-20\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	3029	---	pF
$C_{\text{oss}}$	Output Capacitance		---	129	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	76	---	
Diode Characteristics						
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	-14	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1.2	V
$t_{\text{rr}}$	Reverse Recovery Time	$ I_F =-8\text{A}$ , $dI/dt=-100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	38.7	---	nS
$Q_{\text{rr}}$	Reverse Recovery Charge		---	22.4	---	nC

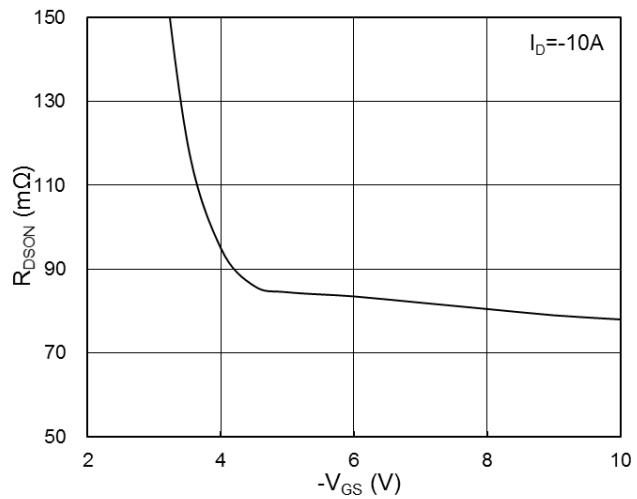
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=-25\text{V}$ ,  $V_{\text{GS}}=-10\text{V}$ ,  $L=0.88\text{mH}$ ,  $I_{\text{AS}}=-18.9\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_s$  , in real applications , should be limited by total power dissipation.

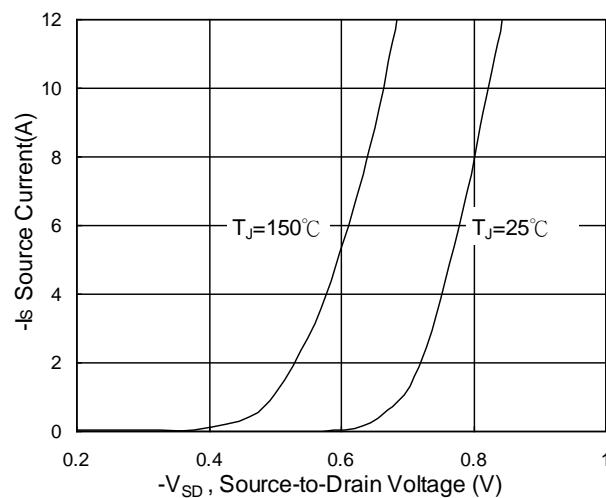
### Typical Characteristics



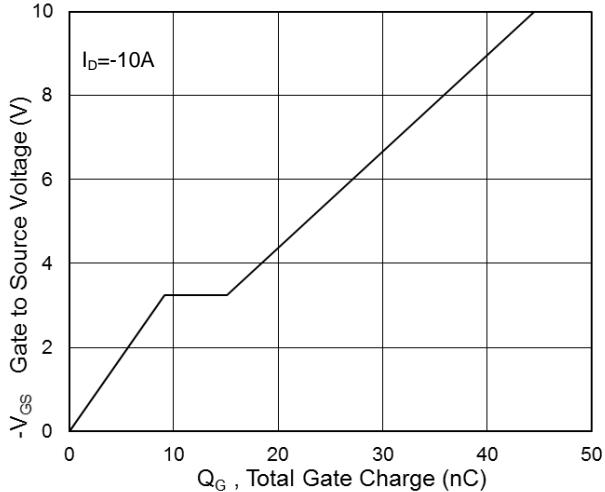
**Fig.1 Typical Output Characteristics**



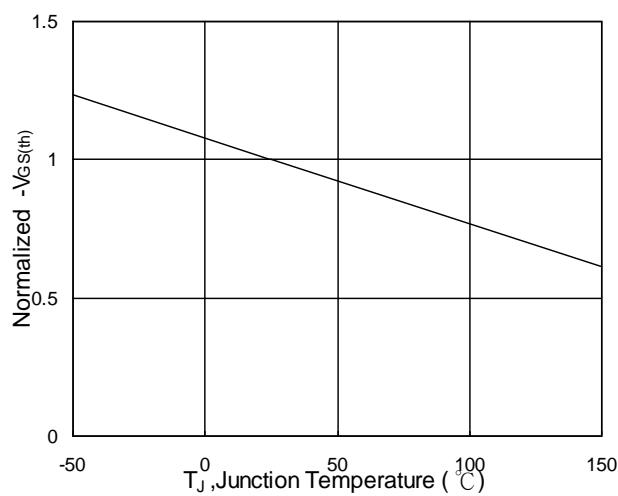
**Fig.2 On-Resistance vs. G-S Voltage**



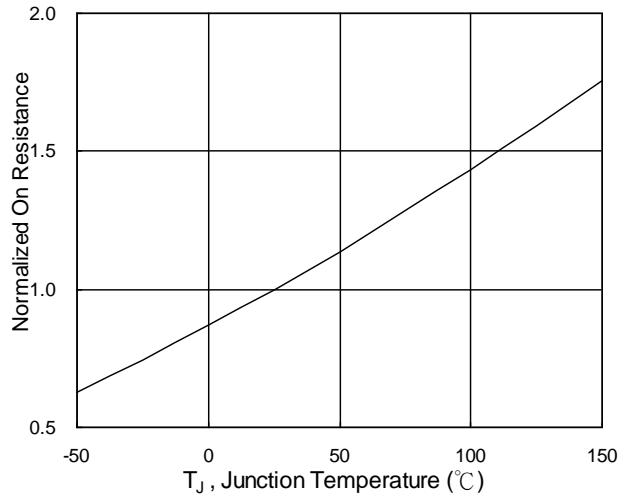
**Fig.3 Typical S-D Diode Forward Voltage**



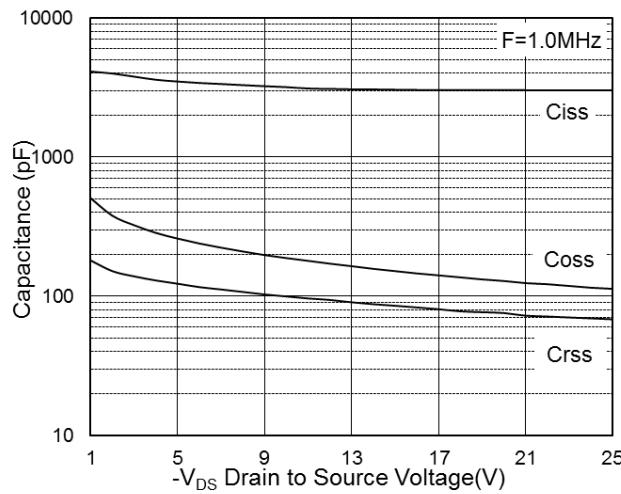
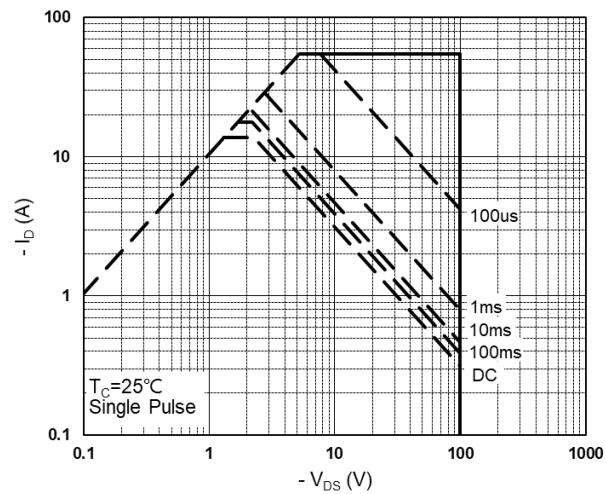
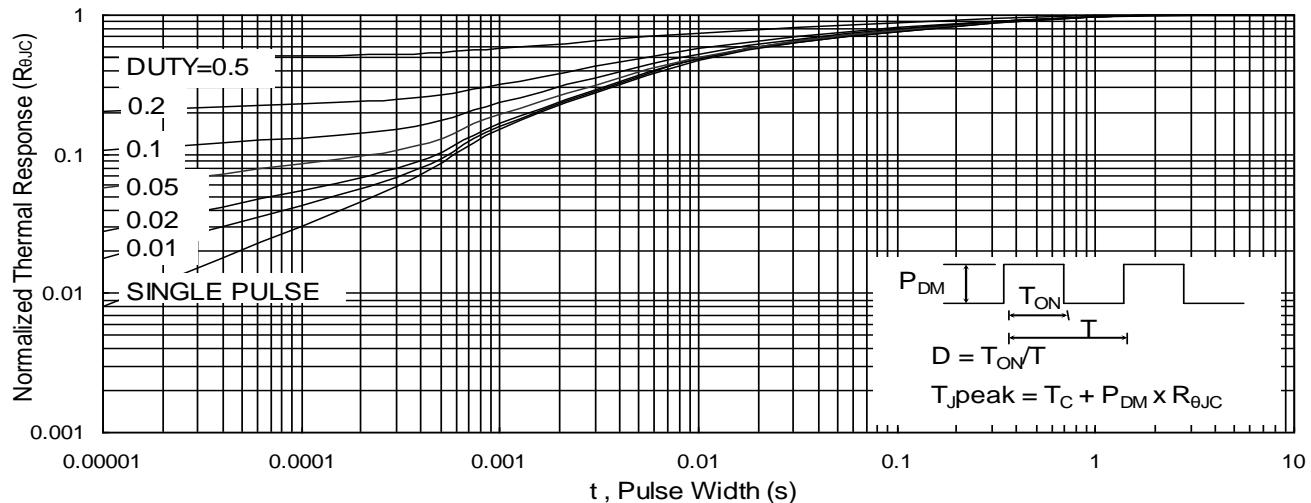
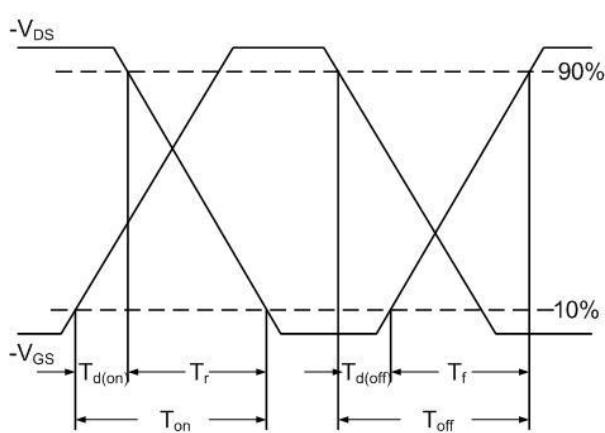
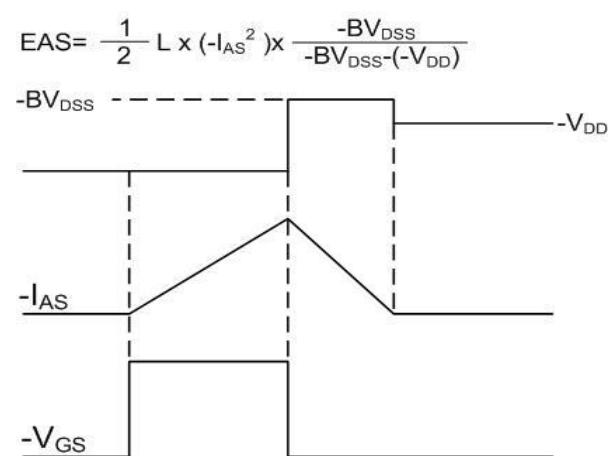
**Fig.4 Gate-Charge Characteristics**



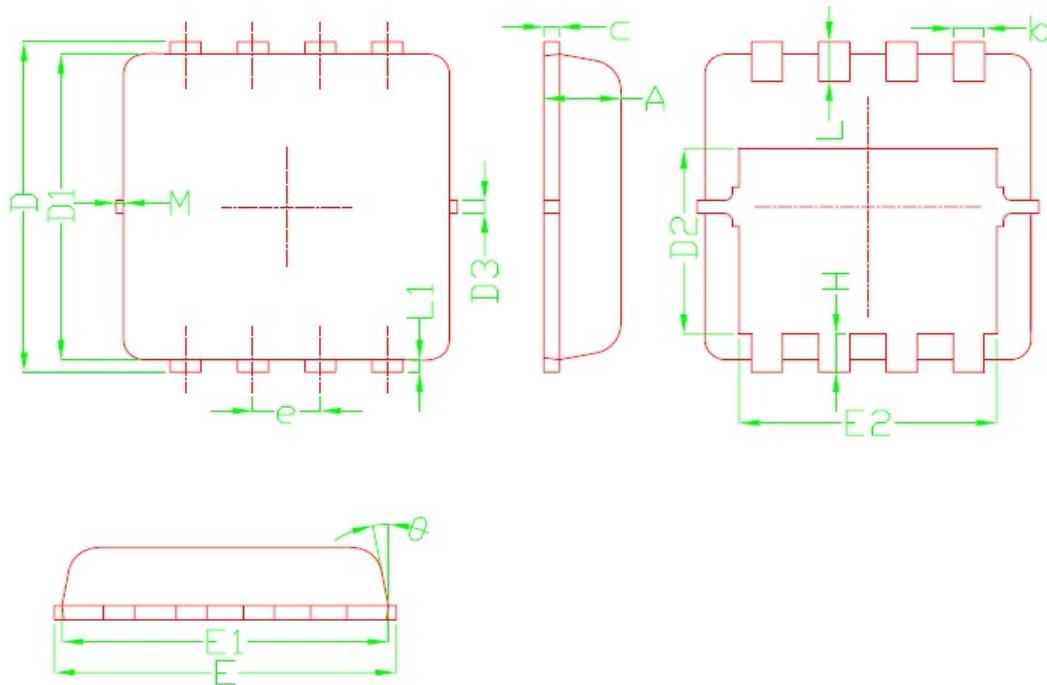
**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**


**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Fig.10 Switching Time Waveform**

**Fig.11 Unclamped Inductive Waveform**

## DFN3x3-8L Package Outline



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.70	0.85	0.027	0.034
b	0.20	0.40	0.007	0.016
c	0.10	0.25	0.004	0.010
D	3.15	3.45	0.124	0.136
D1	2.90	3.20	0.114	0.126
D2	1.54	1.98	0.060	0.080
D3	0.10	0.30	0.004	0.012
E	3.15	3.45	0.124	0.136
E1	3.00	3.25	0.118	0.128
E2	2.29	2.65	0.090	0.104
e	0.65 BSC		0.025 BSC	
H	0.28	0.65	0.011	0.026
$\Theta$	$0^\circ$	$14^\circ$	$0^\circ$	$14^\circ$
L	0.30	0.50	0.012	0.020
L1	0.13		0.005	
M	---	0.15	---	0.006

## Friendship Reminder

- JiNan JingHeng (hereinafter referred to as JH) reserves the right to make changes to this document and its products and specifications at anytime without notice.
- Customers should obtain and confirm the latest product information and specifications before final design, purchase or use.
- JH makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does JH assume any liability for application assistance or customer product design.
- JH does not warrant or accept any liability with products which are purchased or used for any unintended or unauthorized application.
- No license is granted by implication or otherwise under any intellectual property rights of JH.
- JH's products are not authorized for use as critical components in life support devices or systems without express written approval of JH.